

**ON Semiconductor**<sup>®</sup>

## **BSS138** N-Channel Logic Level Enhancement Mode Field Effect Transistor

#### **General Description**

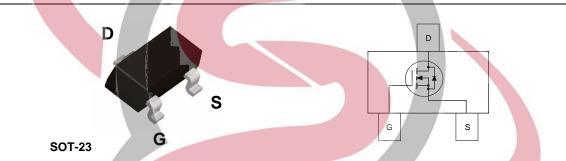
These N-Channel enhancement mode field effect transistors are produced using ON Semicondcutor's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance.These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

### Features

- 0.22 A, 50 V.  $R_{\text{DS(ON)}}=~3.5\Omega$  @  $V_{\text{GS}}$  = 10 V

 $R_{DS(ON)} = 6.0\Omega @ V_{GS} = 4.5 V$ 

- High density cell design for extremely low R<sub>DS(ON)</sub>
- Rugged and Reliable
- Compact industry standard SOT-23 surface mount package



## Absolute Maximum Ratings TA=25°C unless otherwise noted

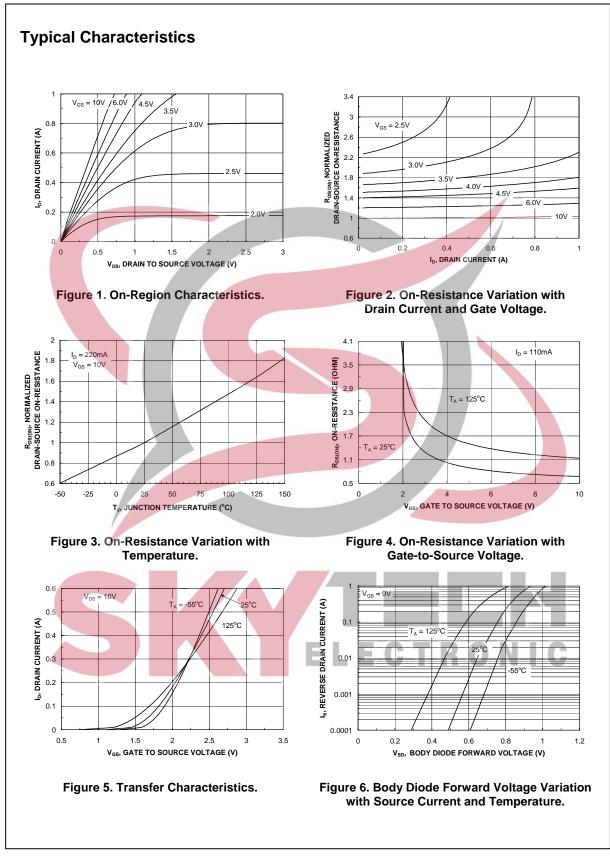
Symbol		Parameter		Ratings	Units	
V <sub>DSS</sub>	Drain-Source Voltage			50	V	
V <sub>GSS</sub>	Gate-Source Voltage			±20		
ID	Drain Current – Continuous (Note 1)			0.22	A	
		- Pulsed		0.88		
PD	Maximum P	ower Dissipation	(Note 1)	0.36	w	
	Derate Above 25°C			2.8	mW/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range			-55 to +150	°C	
TL		ead Temperature for So /16" from Case for 10 S	ECT 300 ON	Cc		
Therma	I Charac	teristics				
$R_{\theta JA}$	Thermal Re	sistance, Junction-to-A	350	°C/W		
Packag	e Markin	g and Ordering	Information			
Device Marking		Device	Reel Size	Tape width	Quantity	
SS		BSS138	7"	8mm	3000 units	

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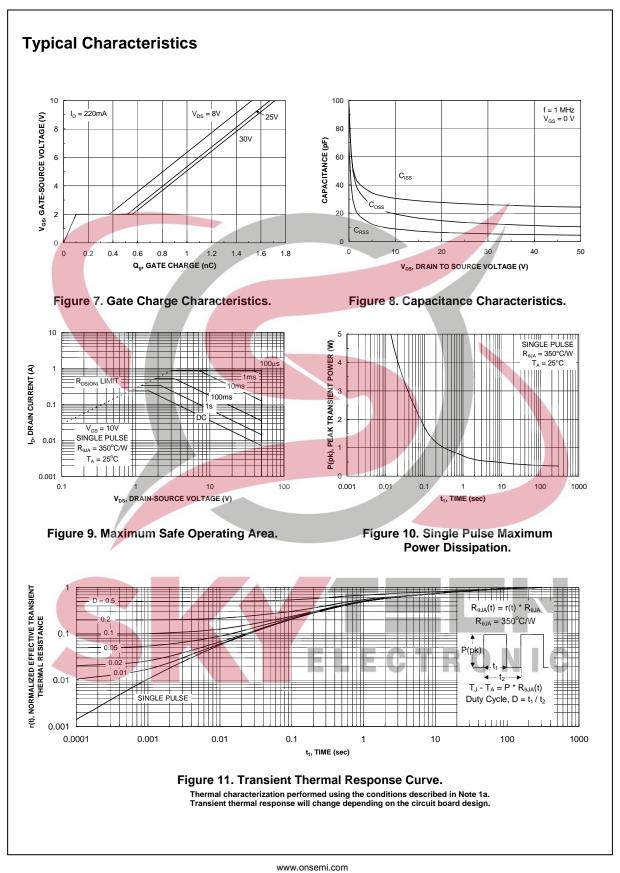
Publication Order Number: BSS138/D

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	Parameter	Test C	Min	Тур	Мах	Units	
Off Chara	acteristics						
BV <sub>DSS</sub>	Drain–Source Breakdown Voltage	$V_{GS} = 0 V$ ,	I <sub>D</sub> = 250 μA	50			V
<u>ΔBV<sub>DSS</sub></u> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA,Re		72		mV/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 50 \text{ V},$	$V_{GS} = 0 V$			0.5	μA
		$V_{DS} = 50 \text{ V}, V_{GS}$			5	μA	
		$V_{\text{DS}}$ = 30 V,	$V_{GS} = 0 V$			100	nA
I <sub>GSS</sub>	Gate-Body Leakage.	$V_{GS} = \pm 20 V$ ,	$V_{DS} = 0 V$			±100	nA
On Chara	acteristics (Note 2)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ ,	$I_D = 1 \text{ mA}$	0.8	1.3	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA,Refe	renced to 25°C		-2		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source	$V_{GS} = 10 V$ ,	-		0.7	3.5	Ω
	On-Resistance	$V_{GS} = 4.5 V,$	I <sub>D</sub> = 0.22 A = 0.22 A, T <sub>J</sub> = 125°C		1.0 1.1	6.0 5.8	
I <sub>D(on)</sub>	On-State Drain Current	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ V},$	$V_{DS} = 5 V$	0.2	1.1	5.0	Α
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10V$ , $V_{DS} = 10V$ ,	$I_{\rm D} = 0.22 \rm{A}$	0.12	0.5		S
-		• 03 = 10 • ;		0.12	0.0		0
	Characteristics				27		~ [
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 V,$ f = 1.0 MHz	$V_{GS} = 0 V,$				рF
C <sub>oss</sub> C <sub>rss</sub>	Output Capacitance Reverse Transfer Capacitance				13 6		pF pF
R <sub>G</sub>	Gate Resistance	$V_{GS} = 15 \text{ mV},$	f = 10 MHz		9		Ω
-		v <sub>GS</sub> = 10 mv,	1 = 1.0 WH 12		3		12
	g Characteristics (Note 2)					-	
t <sub>d(on)</sub>	Turn–On Delay Time	$V_{DD} = 30 V,$ $V_{GS} = 10 V,$	$I_D = 0.29 \text{ A},$ $R_{GEN} = 6 \Omega$		2.5	5	ns
t <sub>r</sub>	Turn–On Rise Time	VGS = 10 V,	INGEN = 0 32		9	18	ns
t <sub>d(off)</sub>	Turn–Off Delay Time				20	36	ns
t <sub>f</sub>		25.14	1 0.00 4		7	14	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 25 V,$ $V_{GS} = 10 V$	$I_{\rm D} = 0.22  {\rm A},$		1.7	2.4	nC
Q <sub>gs</sub>	Gate-Source Charge				0.1		nC
Q <sub>gd</sub>	Gate-Drain Charge				0.4	i	nC
Drain-Sc	ource Diode Characteristics			_	1		
I <sub>S</sub>	Maximum Continuous Drain-Source					0.22	A
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 V,$	I <sub>S</sub> = 0.44 A(Note 2)		0.8	1.4	v
	Vondgo	F	FCT	R			C
R is the su	m of the junction-to-case and case-to-ambient the	rmal resistance where	the case thermal reference	is defined	t as the sc	lder moun	ting surface
	s. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is dete						ang canaco
ן איג	<ul> <li>a) 350°C/W when mounted on a minimum pad</li> </ul>						
cale 1 : 1 on lette	er size paper						



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